TOSHIBA

2020-2-27 Rev.2.0

RD Number: RD099

RD Title: TB67S101ANG Evaluation circuit BOM

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package	Not Mount
1	VM	1	Check terminal	-	_	Check pin		
2	VCC	1	Check terminal	-	_	Check pin		
3	VREFB	1	Check terminal	-	_	Check pin		
4	VREFA	1	Check terminal	-	_	Check pin		
5	OSCM	1	Check terminal	-	_	Check pin		
6	INA1	1	Check terminal	-	_	Check pin		
7	INA2	1	Check terminal	_	_	Check pin		
8	PHASEA	1	Check terminal	_	_	Check pin		
9	PHASEB	1	Check terminal	-	_	Check pin		
10	INB1	1	Check terminal	-	_	Check pin		
11	INB2	1	Check terminal	_	_	Check pin		
12	STANDBY	1	Check terminal	_	_	Check pin		
13	RSA	1	Check terminal	-	_	Check pin		
14	RSB	1	Check terminal	-	_	Check pin		
15	OUT_A+	1	Check terminal	_	_	Check pin		
16	OUT_A-	1	Check terminal	_	_	Check pin		
17	OUT_B+	1	Check terminal	-	_	Check pin		
18	OUT_B-	1	Check terminal	-	_	Check pin		
19	GND1	1	Check terminal	-	_	Check pin		
20	GND2	1	Check terminal	_	_	Check pin		
21	GND3	1	Check terminal	-	_	Check pin		
22	GND4	1	Check terminal	-	_	Check pin		
23	GND5	1	Check terminal	_	_	Check pin		
24	GND6	1	Check terminal	_	_	Check pin		
25	RRSA	1	0.22Ω 1W	_	_	Chip resistor		
26	RRSB	1	0.22Ω 1W	-	_	Chip resistor		

27	RVRF1	1	Socket pin	_	_	Socket pin	
28		0	Not mount	_	_	Leaded resistor	√
29	RVRF2	1	Socket pin	_	_	Socket pin	
30		0	Not mount	_	_	Leaded resistor	√
31	ROSCM	0	Socket pin	_	_	Socket pin	√
32		0	5.1kΩ	_	_	Leaded resistor	√
33		1	5.1kΩ 0.25W	_	_	resistor	
34	COSCM	0	Socket pin	_	_	Socket pin	✓
35		0	270pF 25V	_	_	Leaded capacitor	✓
36		1	270pF 1000V	_	_	Chip capacitor	
37	CVRFA	1	0.1µF 100V	_	_	Chip capacitor	
38	CVRFB	0	0.1µF 100V	_	_	Chip capacitor	✓
39	CVCC	1	0.1µF 100V	_	_	Chip capacitor	
40	CVM3	0	0.1µF 100V	_	_	Chip capacitor	✓
41	CVM2	1	0.1µF 100V	_	_	Chip capacitor	
42	CVM1	1	100µF 50V	_	_	Electrolytic capacitor	
43	CVDD	0	10μF 10V	_	_	Electrolytic capacitor	✓
44	JP1	1	Pin header 2P	_	_	Jumper	
45		1	Jumper socket	_	-	Jumper Short	
46	JP2	1	Pin header 2P	_	_	Jumper	
47		1	Jumper socket	_	_	Jumper Short	
48	SW1(VREFB)	0	Pin header 3P	_	_	Jumper	✓
49		0	Jumper socket	_	-	Jumper Short	✓
50	SW2(INA1)	1	Pin header 3P	_	_	Jumper	
51		1	Jumper socket	_	_	Jumper Short	
52	SW3(INA2)	1	Pin header 3P	_	_	Jumper	
53		1	Jumper socket	_	_	Jumper Short	
54	SW4(PHASEA)	1	Pin header 3P	_	_	Jumper	
55		1	Jumper socket	_	_	Jumper Short	
56	SW5(PHASEB)	1	Pin header 3P	_	_	Jumper	
57		1	Jumper socket	_	_	Jumper Short	
58	SW6(INB1)	1	Pin header 3P	_	_	Jumper	
59		1	Jumper socket	_	_	Jumper Short	
60	SW7(INB2)	1	Pin header 3P	_	_	Jumper	

61		1	Jumper socket	_	_	Jumper Short		
62	SW8(STANDBY)	1	Pin header 3P	_	_	Jumper		
63		1	Jumper socket	_	_	Jumper Short		
64	CNA	1	Terminal block 2P	_	_	Terminal block		
65	CNB	1	Terminal block 2P	_	_	Terminal block		
66	IC1	1	TB67S101ANG	TB67S101ANG	TOSHIBA	Motor driver IC	SDIP24	

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